



NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEG CELCIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.

REVISION HISTORY

ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	1	PRODUCTION	EDWIN L.	04-20-11

APPROVALS

PCB DES. KT

APP ENG. EDWIN L.

SCALE = NONE



1630 MCCARTHY BLVD
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FOR CUSTOMER USE ONLY

TITLE: TOP ASSEMBLY DRAWING

1.5A, LOW NOISE, NEGATIVE REGULATOR
WITH PRECISION CURRENT LIMIT

SIZE N/A IC NO. LT3015EDD
DEMO CIRCUIT 1728A

REV.
1

FILENAME: DC1728A-1.PCB

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